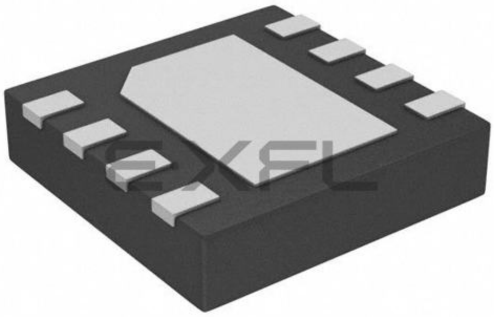
Microchip Technology - PIC12LF1822-E/MF Datasheet



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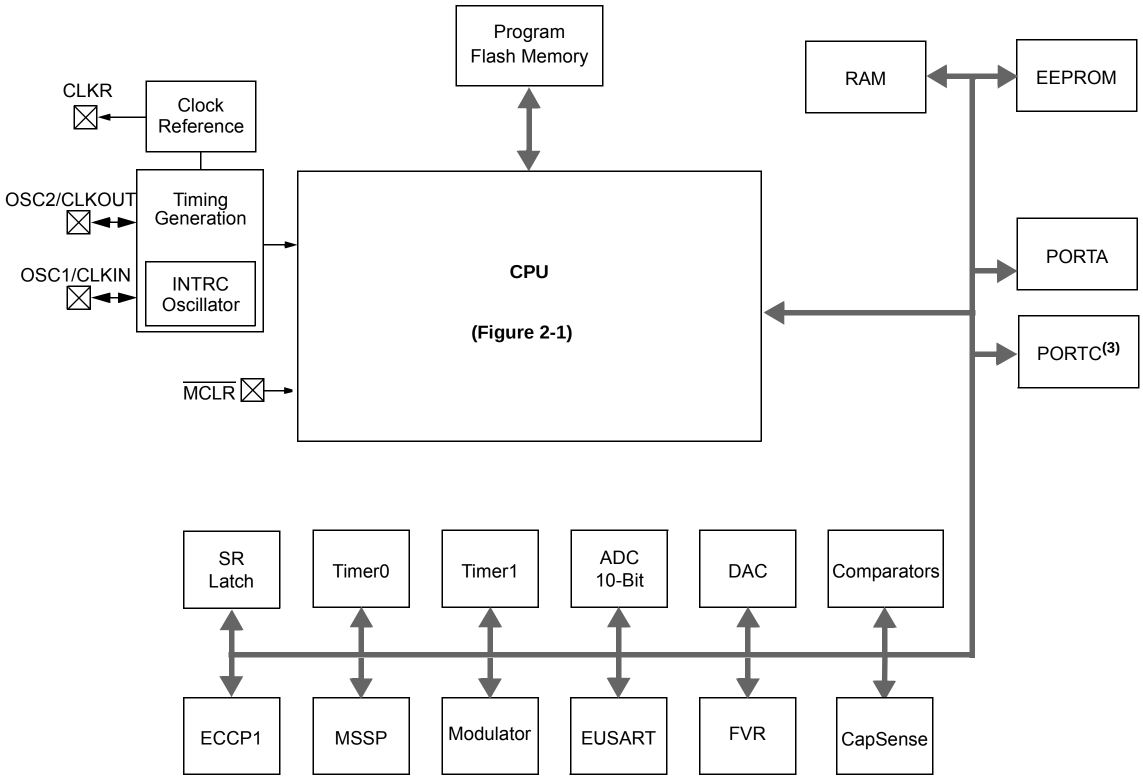
Applications of "Embedded - Microcontrollers"

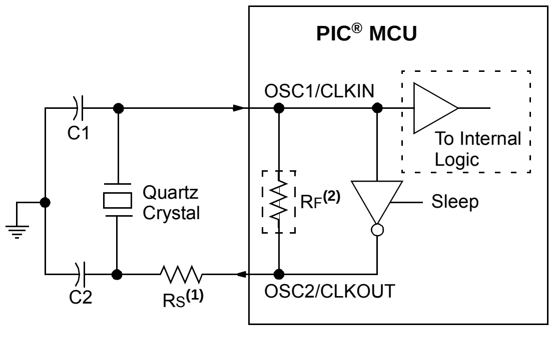
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	6
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 4x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12lf1822-e-mf

FIGURE 1-1: PIC12(L)F1822/16(L)F1823 BLOCK DIAGRAM



Note 1: See applicable chapters for more information on peripherals.
2: See Table 1-1 for peripherals available on specific devices.
3: PIC16(L)F1823 only.

FIGURE 5-3: QUARTZ CRYSTAL OPERATION (LP, XT OR HS MODE)



Note 1: A series resistor (RS) may be required for quartz crystals with low drive level.

2: The value of RF varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

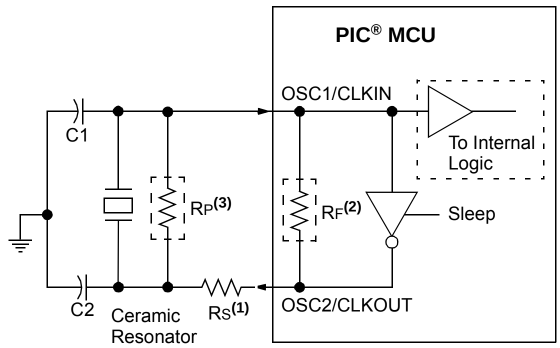
Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the VDD and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Applications Notes:

- AN826, "*Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices*" (DS00826)
- AN849, "*Basic PIC® Oscillator Design*" (DS00849)
- AN943, "*Practical PIC® Oscillator Analysis and Design*" (DS00943)
- AN949, "*Making Your Oscillator Work*" (DS00949)

FIGURE 5-4: CERAMIC RESONATOR OPERATION (XT OR HS MODE)



Note 1: A series resistor (RS) may be required for ceramic resonators with low drive level.

2: The value of RF varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

3: An additional parallel feedback resistor (RP) may be required for proper ceramic resonator operation.

5.2.1.3 Oscillator Start-up Timer (OST)

If the oscillator module is configured for LP, XT or HS modes, the Oscillator Start-up Timer (OST) counts 1024 oscillations from OSC1. This occurs following a Power-on Reset (POR) and when the Power-up Timer (PWRT) has expired (if configured), or a wake-up from Sleep. During this time, the program counter does not increment and program execution is suspended. The OST ensures that the oscillator circuit, using a quartz crystal resonator or ceramic resonator, has started and is providing a stable system clock to the oscillator module.

In order to minimize latency between external oscillator start-up and code execution, the Two-Speed Clock Start-up mode can be selected (see **Section 5.4 "Two-Speed Clock Start-up Mode"**).

5.2.1.4 4X PLL

The oscillator module contains a 4X PLL that can be used with both external and internal clock sources to provide a system clock source. The input frequency for the 4X PLL must fall within specifications. See the PLL Clock Timing Specifications in **Section 30.0 "Electrical Specifications"**.

The 4X PLL may be enabled for use by one of two methods:

1. Program the PLLEN bit in Configuration Word 2 to a '1'.
2. Write the SPLLEN bit in the OSCCON register to a '1'. If the PLLEN bit in Configuration Word 2 is programmed to a '1', then the value of SPLLEN is ignored.

5.4.2 TWO-SPEED START-UP SEQUENCE

1. Wake-up from Power-on Reset or Sleep.
2. Instructions begin execution by the internal oscillator at the frequency set in the IRCF<3:0> bits of the OSCCON register.
3. OST enabled to count 1024 clock cycles.
4. OST timed out, wait for falling edge of the internal oscillator.
5. OSTS is set.
6. System clock held low until the next falling edge of new clock (LP, XT or HS mode).
7. System clock is switched to external clock source.

5.4.3 CHECKING TWO-SPEED CLOCK STATUS

Checking the state of the OSTS bit of the OSCSTAT register will confirm if the microcontroller is running from the external clock source, as defined by the FOSC<2:0> bits in the Configuration Word 1, or the internal oscillator.

FIGURE 5-8: TWO-SPEED START-UP

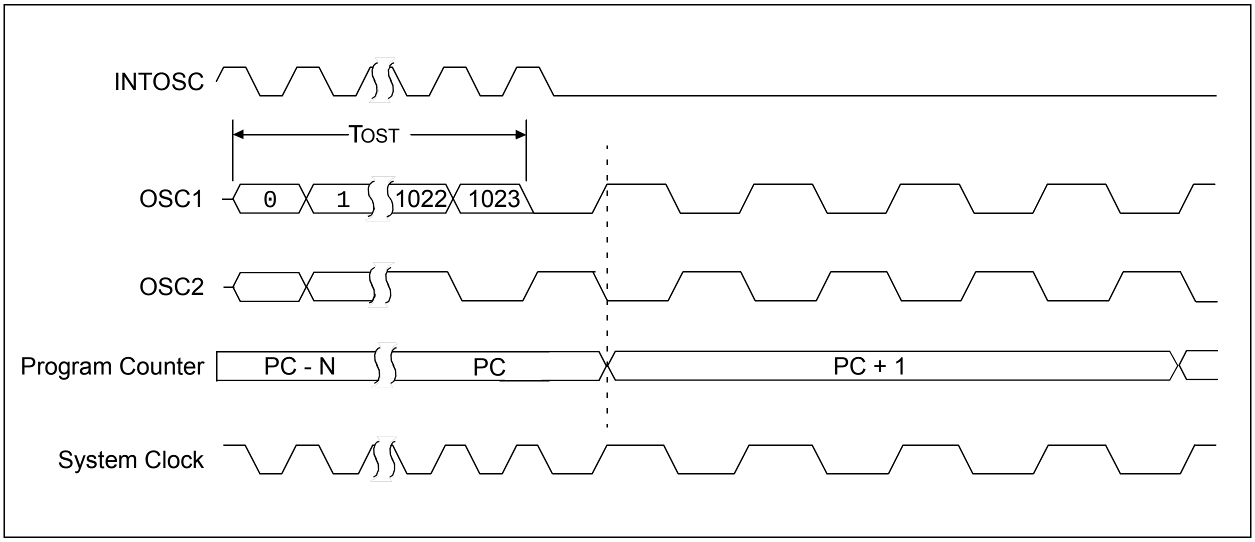


TABLE 9-1: SUMMARY OF REGISTERS ASSOCIATED WITH POWER-DOWN MODE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	86
IOCAF	—	—	IOCAF5	IOCAF4	IOCAF3	IOCAF2	IOCAF1	IOCAF0	125
IOCAN	—	—	IOCAN5	IOCAN4	IOCAN3	IOCAN2	IOCAN1	IOCAN0	125
IOCAP	—	—	IOCAP5	IOCAP4	IOCAP3	IOCAP2	IOCAP1	IOCAP0	125
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	87
PIE2	OSFIE	C2IE(1)	C1IE	EEIE	BCL1IE	—	—	—	88
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	89
PIR2	OSFIF	C2IF(1)	C1IF	EEIF	BCL1IF	—	—	—	90
STATUS	—	—	—	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	20
WDTCON	—	—	WDTPS4	WDTPS3	WDTPS2	WDTPS1	WDTPS0	SWDTEN	97

Legend: — = unimplemented, read as '0'. Shaded cells are not used in Power-Down mode.

Note 1: PIC16(L)F1823 only.

REGISTER 11-1: EEDATL: EEPROM DATA REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
EEDAT<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **EEDAT<7:0>**: Read/write value for EEPROM data byte or Least Significant bits of program memory

REGISTER 11-2: EEDATH: EEPROM DATA HIGH BYTE REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	EEDAT<13:8>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **EEDAT<13:8>**: Read/write value for Most Significant bits of program memory

REGISTER 11-3: EEADRL: EEPROM ADDRESS REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
EEADR<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **EEADR<7:0>**: Specifies the Least Significant bits for program memory address or EEPROM address

REGISTER 11-4: EEADRH: EEPROM ADDRESS HIGH BYTE REGISTER

U-1	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—(1)	EEADR<14:8>						
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **Unimplemented:** Read as '1'

bit 6-0 **EEADR<14:8>**: Specifies the Most Significant bits for program memory address or EEPROM address

Note 1: Unimplemented, read as '1'.

REGISTER 23-4: MDCARL: MODULATION LOW CARRIER CONTROL REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
MDCLODIS	MDCLPOL	MDCLSYNC	—	MDCL<3:0>			
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **MDCLODIS:** Modulator Low Carrier Output Disable bit
- `1` = Output signal driving the peripheral output pin (selected by MDCL<3:0> of the MDCARL register) is disabled
- `0` = Output signal driving the peripheral output pin (selected by MDCL<3:0> of the MDCARL register) is enabled

bit 6 **MDCLPOL:** Modulator Low Carrier Polarity Select bit
- `1` = Selected low carrier signal is inverted
- `0` = Selected low carrier signal is not inverted

bit 5 **MDCLSYNC:** Modulator Low Carrier Synchronization Enable bit
- `1` = Modulator waits for a falling edge on the low time carrier signal before allowing a switch to the high time carrier
- `0` = Modulator Output is not synchronized to the low time carrier signal(1)

bit 4 **Unimplemented:** Read as ‘`0`’

bit 3-0 **MDCL<3:0>** Modulator Data High Carrier Selection bits (1)
- `1111` = Reserved. No channel connected.
- •
- •
- •
- `0101` = Reserved. No channel connected.
- `0100` = CCP1 output (PWM Output mode only)
- `0011` = Reference Clock module signal
- `0010` = Reserved. No channel connected.
- `0001` = MDCIN1 port pin
- `0000` = VSS

Note 1: Narrowed carrier pulse widths or spurs may occur in the signal stream if the carrier is not synchronized.

24.3.6 OPERATION IN SLEEP MODE

In Sleep mode, the TMR2 register will not increment and the state of the module will not change. If the CCP1 pin is driving a value, it will continue to drive that value. When the device wakes up, TMR2 will continue from its previous state.

24.3.7 CHANGES IN SYSTEM CLOCK FREQUENCY

The PWM frequency is derived from the system clock frequency. Any changes in the system clock frequency will result in changes to the PWM frequency. See **Section 5.0 "Oscillator Module (With Fail-Safe Clock Monitor)"** for additional details.

24.3.8 EFFECTS OF RESET

Any Reset will force all ports to Input mode and the CCP registers to their Reset states.

24.3.9 ALTERNATE PIN LOCATIONS

This module incorporates I/O pins that can be moved to other locations with the use of the alternate pin function register, APFCON. To determine which pins can be moved and what their default locations are upon a Reset, see **Section 12.1 "Alternate Pin Function"** for more information.

TABLE 24-8: SUMMARY OF REGISTERS ASSOCIATED WITH STANDARD PWM

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
APFCON	RXDTSEL	SDOSEL	SSSEL	—	T1GSEL	TXCKSEL	P1BSEL(2)	CCP1SEL(2)	114
CCP1CON	P1M<1:0>		DC1B<1:0>		CCP1M<3:0>				213
CCPR1L	Capture/Compare/PWM Register x Low Byte (LSB)								191
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	86
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	87
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	89
PR2	Timer2 Period Register								176*
T2CON	—	T2OUTPS<3:0>				TMR2ON	T2CKPS<:0>1		178
TMR2	Timer2 Module Register								176*
TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	117
TRISC(1)	—	—	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	121

Legend: — = Unimplemented location, read as '0'. Shaded cells are not used by the PWM.
* Page provides register information.
Note 1: PIC16(L)F1823 only.
2: PIC12(L)F1822 only.

REGISTER 25-5: SSP1MSK: SSP1 MASK REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
MSK<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-1 **MSK<7:1>:** Mask bits
`1` = The received address bit n is compared to SSP1ADD<n> to detect I²C address match
`0` = The received address bit n is not used to detect I²C address match

bit 0 **MSK<0>:** Mask bit for I²C Slave mode, 10-bit Address
I²C Slave mode, 10-bit address (SSP1M<3:0> = `0111` or `1111`):
`1` = The received address bit 0 is compared to SSP1ADD<0> to detect I²C address match
`0` = The received address bit 0 is not used to detect I²C address match
I²C Slave mode, 7-bit address, the bit is ignored

REGISTER 25-6: SSP1ADD: MSSP1 ADDRESS AND BAUD RATE REGISTER (I²C MODE)

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
ADD<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

Master mode:

bit 7-0 **ADD<7:0>:** Baud Rate Clock Divider bits
SCL pin clock period = ((ADD<7:0> + 1) *4)/FOSC

10-Bit Slave mode — Most Significant Address byte:

bit 7-3 **Not used:** Unused for Most Significant Address byte. Bit state of this register is a “don’t care”. Bit pattern sent by master is fixed by I²C specification and must be equal to ‘`11110`’. However, those bits are compared by hardware and are not affected by the value in this register.

bit 2-1 **ADD<2:1>:** Two Most Significant bits of 10-bit address

bit 0 **Not used:** Unused in this mode. Bit state is a “don’t care”.

10-Bit Slave mode — Least Significant Address byte:

bit 7-0 **ADD<7:0>:** Eight Least Significant bits of 10-bit address

7-Bit Slave mode:

bit 7-1 **ADD<7:1>:** 7-bit address

bit 0 **Not used:** Unused in this mode. Bit state is a “don’t care”.

26.3.2 AUTO-BAUD OVERFLOW

During the course of automatic baud detection, the ABDOVF bit of the BAUDCON register will be set if the baud rate counter overflows before the fifth rising edge is detected on the RX pin. The ABDOVF bit indicates that the counter has exceeded the maximum count that can fit in the 16 bits of the SPBRGH:SPBRGL register pair. After the ABDOVF has been set, the counter continues to count until the fifth rising edge is detected on the RX pin. Upon detecting the fifth RX edge, the hardware will set the RCIF interrupt flag and clear the ABDEN bit of the BAUDCON register. The RCIF flag can be subsequently cleared by reading the RCREG register. The ABDOVF flag of the BAUDCON register can be cleared by software directly.

To terminate the auto-baud process before the RCIF flag is set, clear the ABDEN bit then clear the ABDOVF bit of the BAUDCON register. The ABDOVF bit will remain set if the ABDEN bit is not cleared first.

26.3.3 AUTO-WAKE-UP ON BREAK

During Sleep mode, all clocks to the EUSART are suspended. Because of this, the Baud Rate Generator is inactive and a proper character reception cannot be performed. The Auto-Wake-up feature allows the controller to wake-up due to activity on the RX/DT line. This feature is available only in Asynchronous mode.

The Auto-Wake-up feature is enabled by setting the WUE bit of the BAUDCON register. Once set, the normal receive sequence on RX/DT is disabled, and the EUSART remains in an Idle state, monitoring for a wake-up event independent of the CPU mode. A wake-up event consists of a high-to-low transition on the RX/DT line. (This coincides with the start of a Sync Break or a wake-up signal character for the LIN protocol.)

The EUSART module generates an RCIF interrupt coincident with the wake-up event. The interrupt is generated synchronously to the Q clocks in normal CPU operating modes (Figure 26-7), and asynchronously if the device is in Sleep mode (Figure 26-8). The interrupt condition is cleared by reading the RCREG register.

The WUE bit is automatically cleared by the low-to-high transition on the RX line at the end of the Break. This signals to the user that the Break event is over. At this point, the EUSART module is in Idle mode waiting to receive the next character.

26.3.3.1 Special Considerations

Break Character

To avoid character errors or character fragments during a wake-up event, the wake-up character must be all zeros.

When the wake-up is enabled the function works independent of the low time on the data stream. If the WUE bit is set and a valid non-zero character is received, the low time from the Start bit to the first rising edge will be interpreted as the wake-up event. The remaining bits in the character will be received as a fragmented character and subsequent characters can result in framing or overrun errors.

Therefore, the initial character in the transmission must be all '0's. This must be 10 or more bit times, 13-bit times recommended for LIN bus, or any number of bit times for standard RS-232 devices.

Oscillator Start-up Time

Oscillator start-up time must be considered, especially in applications using oscillators with longer start-up intervals (i.e., LP, XT or HS/PLL mode). The Sync Break (or wake-up signal) character must be of sufficient length, and be followed by a sufficient interval, to allow enough time for the selected oscillator to start and provide proper initialization of the EUSART.

WUE Bit

The wake-up event causes a receive interrupt by setting the RCIF bit. The WUE bit is cleared in hardware by a rising edge on RX/DT. The interrupt condition is then cleared in software by reading the RCREG register and discarding its contents.

To ensure that no actual data is lost, check the RCIDL bit to verify that a receive operation is not in process before setting the WUE bit. If a receive operation is not occurring, the WUE bit may then be set just prior to entering the Sleep mode.

30.1 DC Characteristics: PIC12(L)F1822/16(L)F1823-I/E (Industrial, Extended)

PIC12LF1822/16LF1823			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
PIC12F1822/16F1823			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**					
		PIC12LF1822/16LF1823	1.8 2.5	— —	3.6 3.6	V V	FOSC ≤ 16 MHz: FOSC ≤ 32 MHz (**Note 2**)
D001		PIC12F1822/16F1823	1.8 2.5	— —	5.5 5.5	V V	FOSC ≤ 16 MHz: FOSC ≤ 32 MHz (**Note 2**)
D002*	VDR	**RAM Data Retention Voltage(1)**					
		PIC12LF1822/16LF1823	1.5	—	—	V	Device in Sleep mode
D002*		PIC12F1822/16F1823	1.7	—	—	V	Device in Sleep mode
	VPOR*	**Power-on Reset Release Voltage**	—	1.6	—	V	
	VPORR*	**Power-on Reset Rearm Voltage**					
		PIC12LF1822/16LF1823	—	0.8	—	V	Device in Sleep mode
		PIC12F1822/16F1823	—	1.4	—	V	Device in Sleep mode
D003	VADFVR	**Fixed Voltage Reference Voltage for ADC**	-8 -8 -8		6 6 6	%	1.024V, VDD ≥ 2.5V 2.048V, VDD ≥ 2.5V 4.096V, VDD ≥ 4.75V
D003A	VCDAFVR	**Fixed Voltage Reference Voltage for Comparator and DAC**	-11 -11 -11		7 7 7	%	1.024V, VDD ≥ 2.5V 2.048V, VDD ≥ 2.5V 4.096V, VDD ≥ 4.75V
D003C*	TCVFVR	Temperature Coefficient, Fixed Voltage Reference	—	-114	—	ppm/°C	
D003D*	ΔVFVR/ΔVIN	Line Regulation, Fixed Voltage Reference	—	0.225	—	%/V	
D004*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	See **Section 7.1 “Power-on Reset (POR)”** for details.

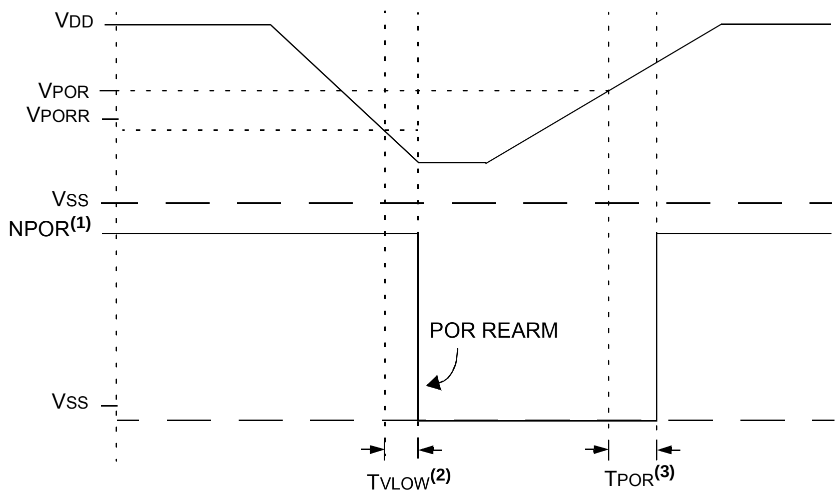
* These parameters are characterized but not tested.

† Data in “Typ” column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

2: PLL required for 32 MHz operation.

FIGURE 30-4: POR AND POR REARM WITH SLOW RISING VDD



Note 1: When NPOR is low, the device is held in Reset.
2: TPOR 1 μs typical.
3: TVLOW 2.7 μs typical.

TABLE 30-16: I²C™ BUS DATA REQUIREMENTS

Param. No.	Symbol	Characteristic		Min.	Max.	Units	Conditions
SP100*	THIGH	Clock high time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a minimum of 10 MHz
			SSPx module	1.5TCY	—	—	
SP101*	TLOW	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a minimum of 10 MHz
			SSPx module	1.5TCY	—	—	
SP102*	TR	SDAx and SCLx rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1CB	300	ns	CB is specified to be from 10-400 pF
SP103*	TF	SDAx and SCLx fall time	100 kHz mode	—	250	ns	
			400 kHz mode	20 + 0.1CB	250	ns	CB is specified to be from 10-400 pF
SP106*	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
SP107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
SP109*	TAA	Output valid from clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
SP110*	TBUF	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
SP111	CB	Bus capacitive loading		—	400	pF	

* These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCLx to avoid unintended generation of Start or Stop conditions.

2: A Fast mode (400 kHz) I²C™ bus device can be used in a Standard mode (100 kHz) I²C bus system, but the requirement TSU:DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the low period of the SCLx signal. If such a device does stretch the low period of the SCLx signal, it must output the next data bit to the SDAx line TR max. + TSU:DAT = 1000 + 250 = 1250 ns (according to the Standard mode I²C bus specification), before the SCLx line is released.

TABLE 30-23: A/D CONVERTER (ADC) CHARACTERISTICS FOR PIC12F1822/16F1823-H (High Temp.)

PIC12F1822/16F1823			**Standard Operating Conditions: (unless otherwise stated)** Operating Temperature: -40°C ≤ T_A ≤ +150°C for High Temperature				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
AD04	E_{OFF}	Offset Error	—	—	3.5	LSB	No missing codes V_{REF} = 3.0V

† Data in “Typ” column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Total Absolute Error includes integral, differential, offset and gain errors.

2: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

3: ADC V_{REF} is from external V_{REF}, V_{DD} pin or FVR, whichever is selected as reference input.

TABLE 30-24: COMPARATOR SPECIFICATIONS FOR PIC12F1822/16F1823-H (High Temp.)

PIC12F1822/16F1823			**Standard Operating Conditions: (unless otherwise stated)** Operating Temperature: -40°C ≤ T_A ≤ +150°C for High Temperature				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
CM01	V_{IOFF}	Input Offset Voltage	—	—	±70	mV	High-Power mode, V_{ICM} = V_{DD}/2

TABLE 30-25: CAP SENSE OSCILLATOR SPECIFICATIONS FOR PIC12F1822/16F1823-H (High Temp.)

PIC12F1822/16F1823			**Standard Operating Conditions: (unless otherwise stated)** Operating Temperature: -40°C ≤ T_A ≤ +150°C for High Temperature				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
All	All	All	—	—	—	—	This module is not intended for use in high temperature devices.

FIGURE 31-1: IDD, LP OSCILLATOR MODE (FOSC = 32 kHz), PIC12LF1822 AND PIC16LF1823 ONLY

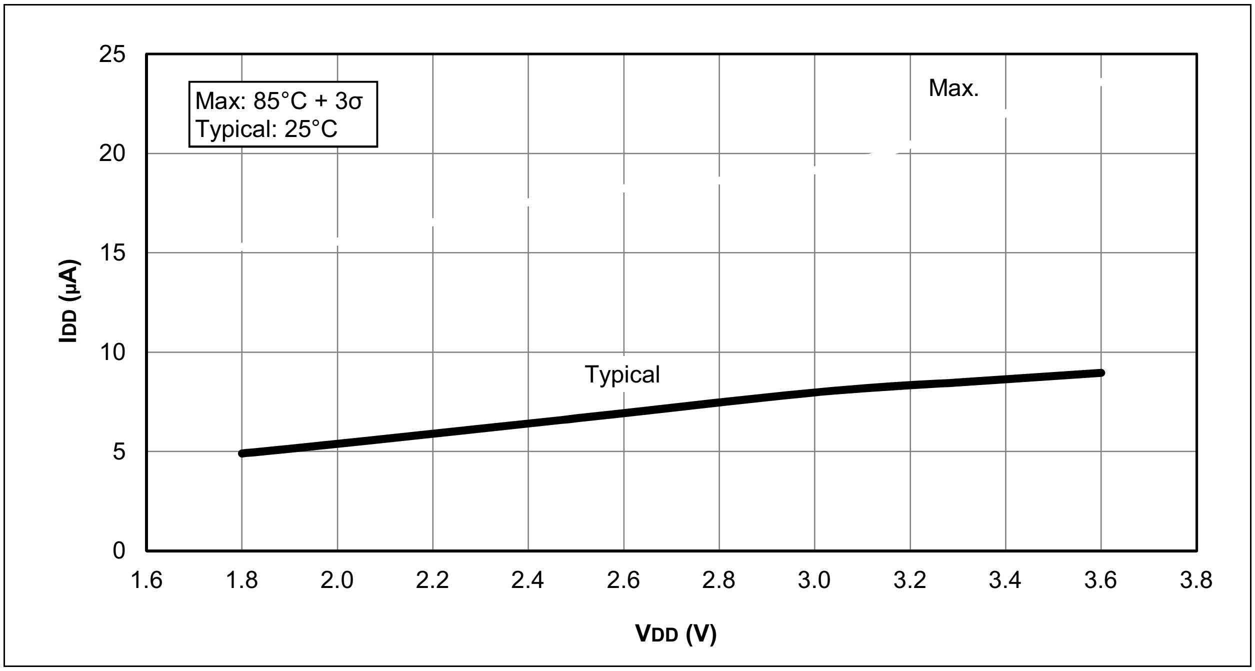


FIGURE 31-2: IDD, LP OSCILLATOR MODE (FOSC = 32 kHz), PIC12F1822 AND PIC16F1823 ONLY

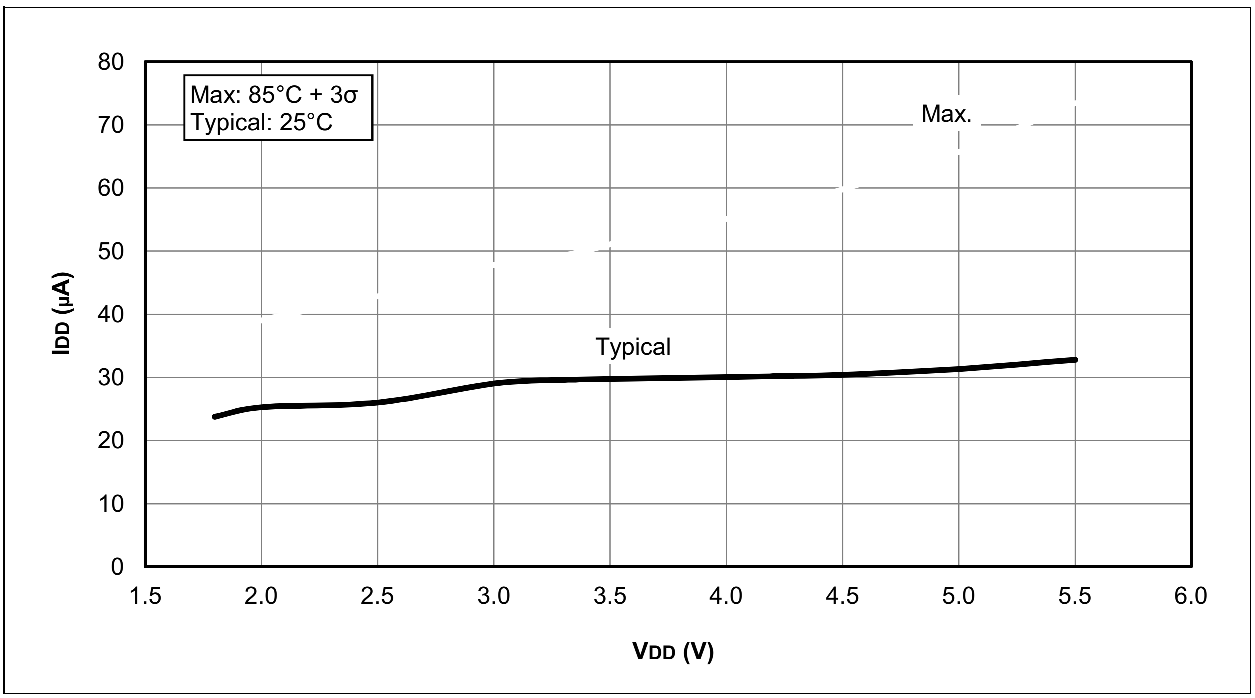


FIGURE 31-9: IDD, EC OSCILLATOR, LOW-POWER MODE (FOSC = 500 kHz), PIC12LF1822 AND PIC16LF1823 ONLY

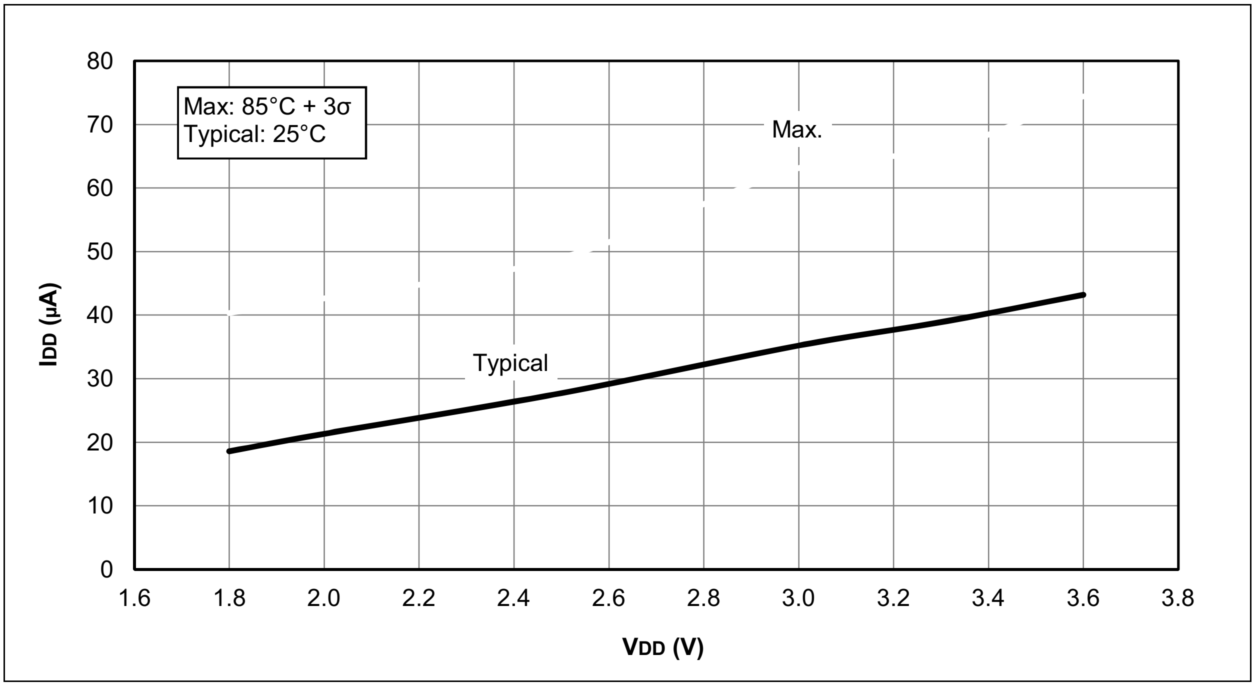


FIGURE 31-10: IDD, EC OSCILLATOR, LOW-POWER MODE (FOSC = 500 kHz), PIC12F1822 AND PIC16F1823 ONLY

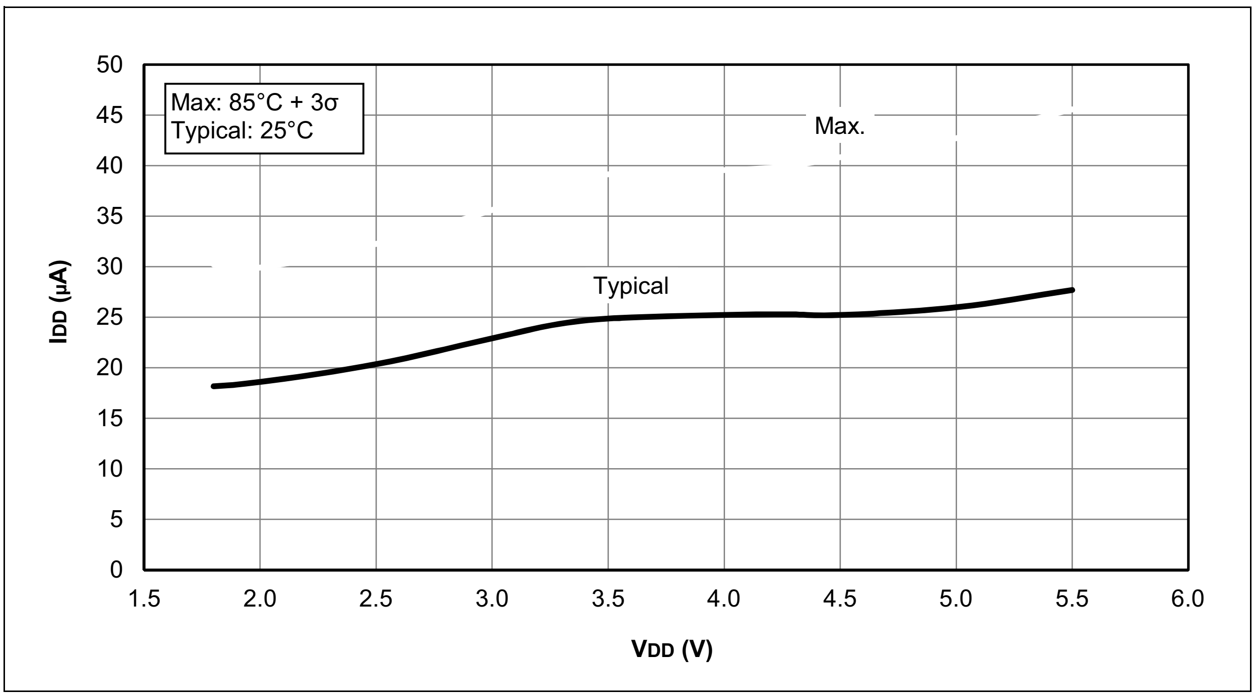


FIGURE 31-23: IDD TYPICAL, HFINTOSC MODE, PIC12LF1822 AND PIC16LF1823 ONLY

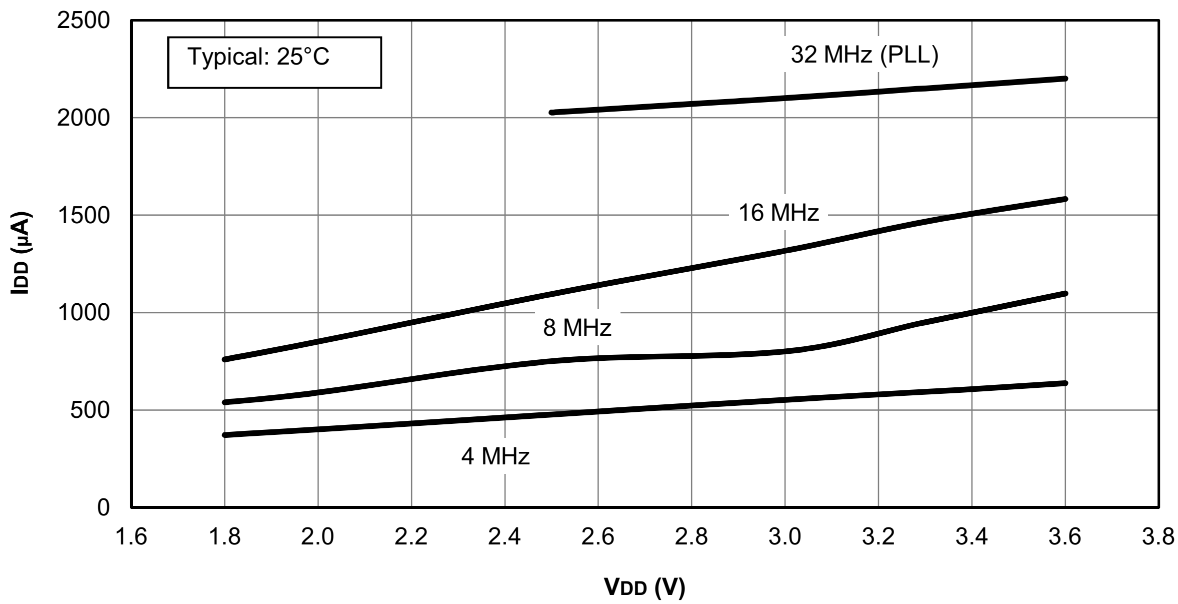


FIGURE 31-24: IDD MAXIMUM, HFINTOSC MODE, PIC12LF1822 AND PIC16LF1823 ONLY

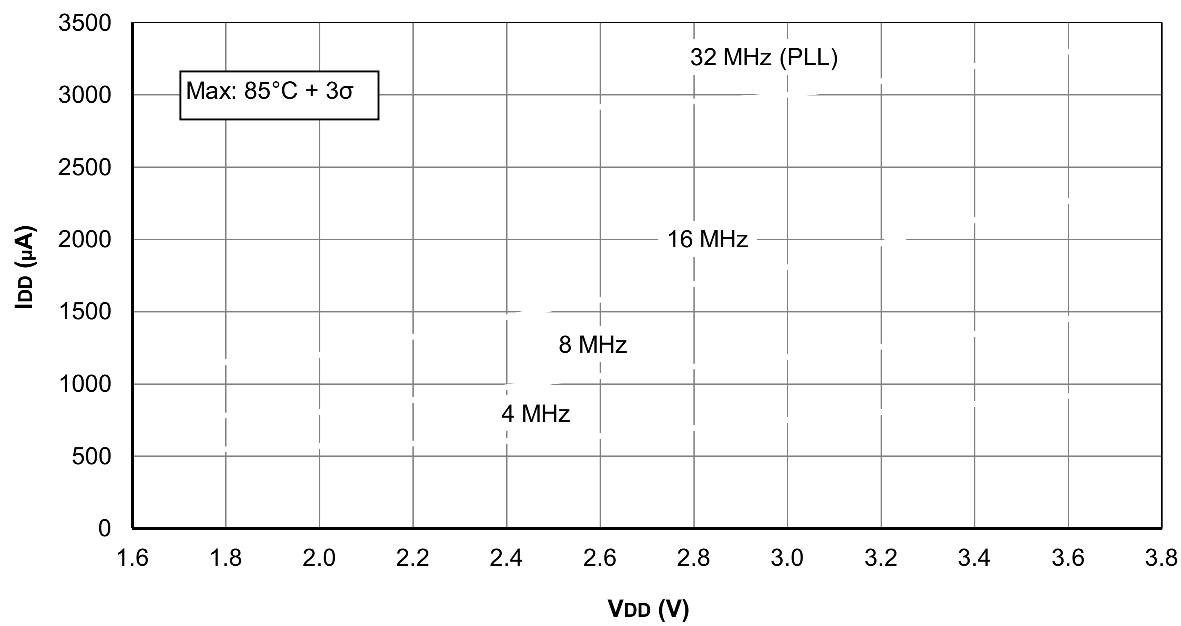


FIGURE 31-33: IPD, WATCHDOG TIMER (WDT), PIC12LF1822 AND PIC16LF1823 ONLY

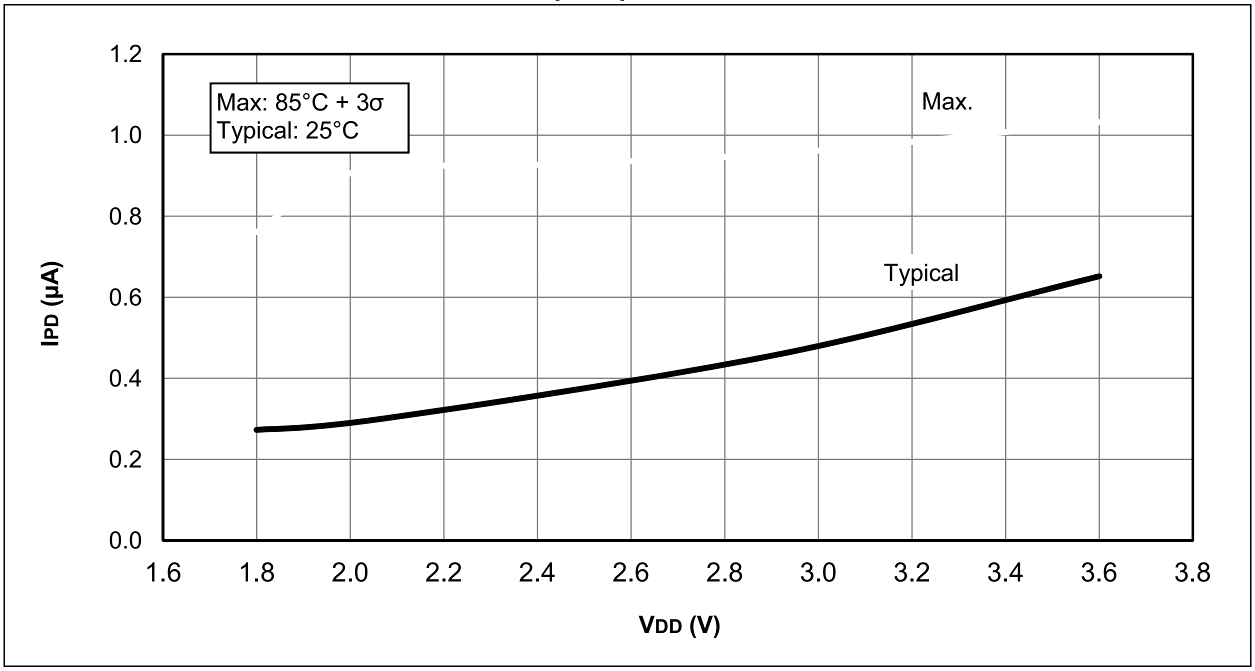
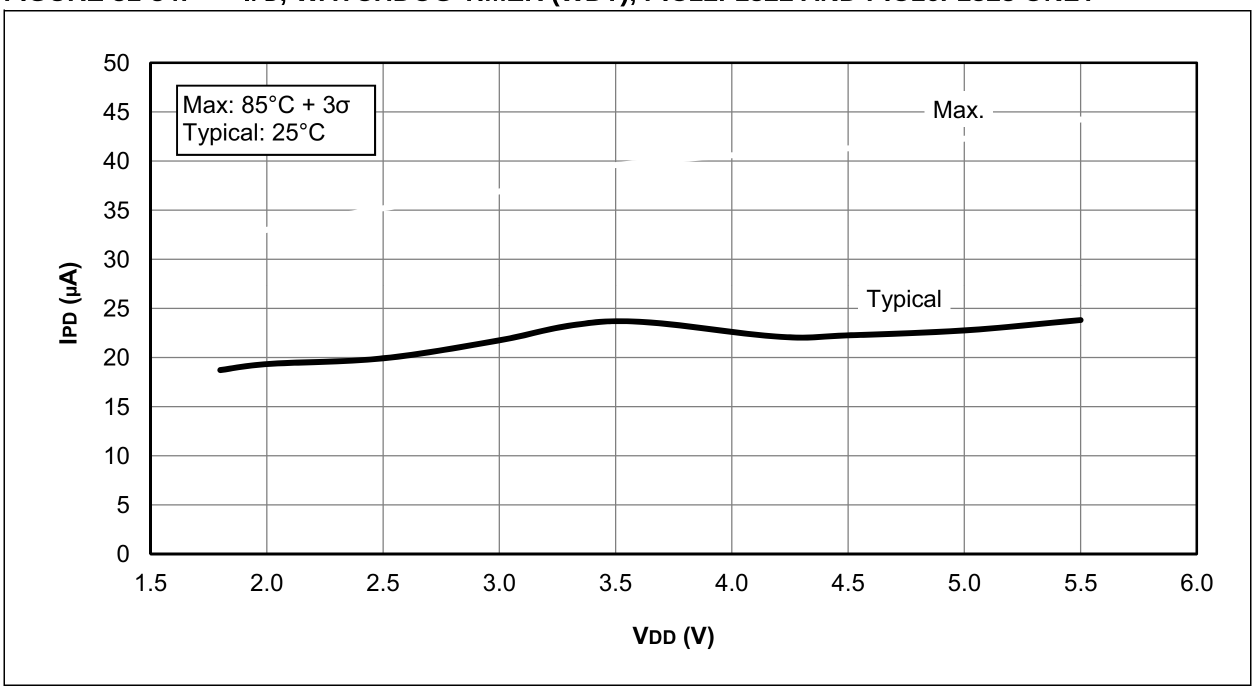


FIGURE 31-34: IPD, WATCHDOG TIMER (WDT), PIC12F1822 AND PIC16F1823 ONLY



32.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

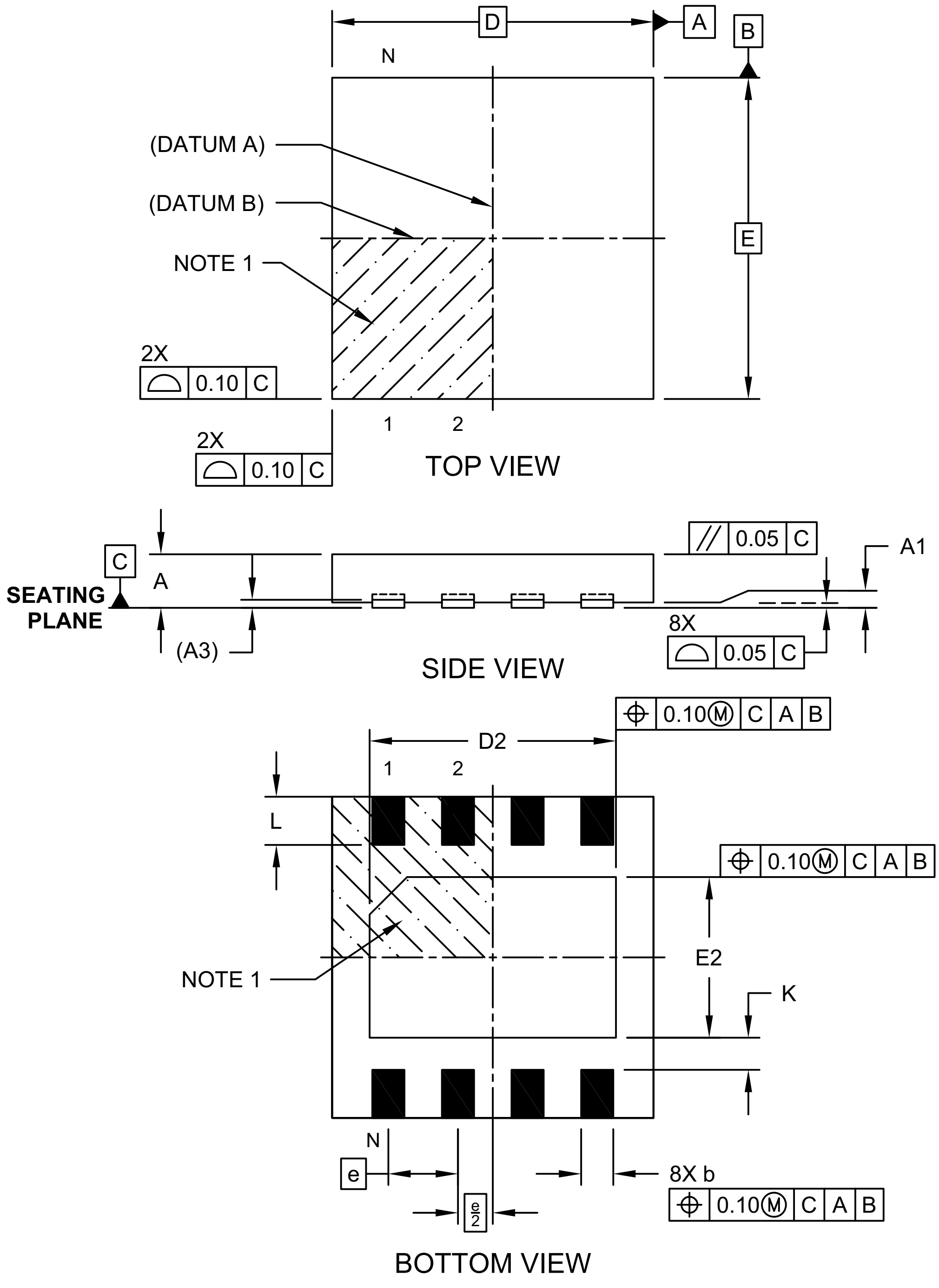
32.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

8-Lead Ultra Thin Plastic Dual Flat, No Lead Package (RF) - 3x3x0.50 mm Body [UDFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-254A Sheet 1 of 2

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	[X]	- X	/XX	XXX
Device	Tape and Reel Option	Temperature Range	Package	Pattern

Device:	PIC12F1822, PIC12LF1822 PIC16F1823, PIC16LF1823
Tape and Reel Option:	Blank = standard packaging (tube or tray) T = Tape and Reel(1)
Temperature Range:	I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)
Package:(2)	JQ = Micro Lead Frame (UQFN) 4x4x0.5mm MF = Micro Lead Frame (DFN) 3x3x0.9mm ML = Micro Lead Frame (QFN) 4x4x0.9mm P = Plastic DIP RF = Micro Lead Frame (UDFN) 3x3x0.5mm SL = SOIC SN = SOIC ST = TSSOP
Pattern:	QTP, SQTP, Code or Special Requirements (blank otherwise)

Examples:

a) PIC12F1822 - I/MF 301 = Industrial temp., DFN package, QTP pattern #301.

b) PIC16F1823 - I/P = Industrial temp., PDIP package.

c) PIC16F1823 - E/ST= Extended temp., TSSOP package.

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

2: Small-form factor packaging options may be available. Please check www.microchip.com/packaging for small form-factor package availability, or contact your local Sales Office.